L Number	Hits	Search Text	DB	Time st
1	20324	flip NEAR chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
2	20325	flip NEAR chip$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
3	120	(flip NEAR chip$1) and ((die NEAR pad$4) WITH (concavit$3 hollow open$3 hole$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
4	19	(flip NEAR chip$1) and ((die NEAR pad$4) WITH (concavit$3 hollow open$3 hole$1) WITH bump$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
5	28	("3648002" | "3832632" | "3971610" | "4288841" | "4329642" | "4340860" | "4437718" | "4554505" | "4739257" | "4899107" | "4956605" | "5006792" | "5006796" | "5014161" | "5061192" | "5123850" | "5173451" | "5207585" | "5248262" | "5302891" | "5329423" | "5358417" | "5453701" | "5475315" | "5489854" | "5493237" | "5633596" | "5656945").PN.	USPAT	2004/0:
6	93	((flip NEAR chip$1) and ((die NEAR pad$4) WITH (concavit$3 hollow open$3 hole$1))) and bump$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
7	74	(((flip NEAR chip$1) and ((die NEAR pad$4) WITH (concavit$3 hollow open$3 hole$1))) and bump$1) and (bond$3 NEAR pad$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
8	53	(flip NEAR chip$1) and ((lead NEAR frame) WITH (tie NEAR bar$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
9	7	("5091341" | "5147821" | "5200809" | "5202288" | "5387554" | "5442234" | "5570272").PN.	USPAT	2004/0:
10	6	("3729573" | "4377548" | "4470786" | "4626185" | "4823234" | "4954307").PN.	USPAT	2004/0:
11	34	((die NEAR pad$4) WITH (concavit$3 hollow open$3 hole$1) WITH bump$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
12	994	(die NEAR pad$4) WITH (concavit$3 hollow open$3 hole$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
13	79	((die NEAR pad$4) WITH (concavit$3 hollow open$3 hole$1)) and ((lead NEAR frame) WITH (tie NEAR bar$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:

L Number	Hits	Search Text	DB	Time st
1	20324	flip NEAR chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
2	20325	flip NEAR chip$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
3	120	(flip NEAR chip$1) and ((die NEAR pad$4) WITH (concavit$3 hollow open$3 hole$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
4	19	(flip NEAR chip$1) and ((die NEAR pad$4) WITH (concavit$3 hollow open$3 hole$1) WITH bump$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
5	28	("3648002" | "3832632" | "3971610" | "4288841" | "4329642" | "4340860" | "4437718" | "4554505" | "4739257" | "4899107" | "4956605" | "5006792" | "5006796" | "5014161" | "5061192" | "5123850" | "5173451" | "5207585" | "5248262" | "5302891" | "5329423" | "5358417" | "5453701" | "5475315" | "5489854" | "5493237" | "5633596" | "5656945").PN.	USPAT	2004/0:
6	93	((flip NEAR chip$1) and ((die NEAR pad$4) WITH (concavit$3 hollow open$3 hole$1))) and bump$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
7	74	(((flip NEAR chip$1) and ((die NEAR pad$4) WITH (concavit$3 hollow open$3 hole$1))) and bump$1) and (bond$3 NEAR pad$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
8	53	(flip NEAR chip$1) and ((lead NEAR frame) WITH (tie NEAR bar$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
9	7	("5091341" | "5147821" | "5200809" | "5202288" | "5387554" | "5442234" | "5570272").PN.	USPAT	2004/0:
10	6	("3729573" | "4377548" | "4470786" | "4626185" | "4823234" | "4954307").PN.	USPAT	2004/0:
11	34	((die NEAR pad$4) WITH (concavit$3 hollow open$3 hole$1) WITH bump$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
12	994	(die NEAR pad$4) WITH (concavit$3 hollow open$3 hole$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
13	79	((die NEAR pad$4) WITH (concavit$3 hollow open$3 hole$1)) and ((lead NEAR frame) WITH (tie NEAR bar$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:

14	18	thermal$2 NEAR conduct$3 NEAR bump$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
15	2	("6331451").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
16	0	("2and((heatNEARspreader)WITHchip)").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
17	303	(flip NEAR chip$1) and ((heat NEAR spreader) WITH chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
18	0	((flip NEAR chip$1) and ((heat NEAR spreader) WITH chip)) and ((die NEAR pad$4) WITH (concavit$3 hollow open$3 hole$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
19	0	((flip NEAR chip$1) and ((heat NEAR spreader) WITH chip)) and ((lead NEAR frame) WITH (tie NEAR bar$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
20	186	((flip NEAR chip$1) and ((heat NEAR spreader) WITH chip)) and bump$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
21	77	(((flip NEAR chip$1) and ((heat NEAR spreader) WITH chip)) and bump$1) and (bond$3 NEAR pad$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
22	0	(flip NEAR chip$1) and (heat NEAR transmission NEAR (layer film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
23	1	chip WITH (heat NEAR transmission NEAR (layer film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
24	7	chip and (heat NEAR transmission NEAR (layer film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
25	0	(active NEAR surface NEAR chip) WITH (electrically NEAR connect$3) WITH (tie NEAR bar$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:

27	7	(chip$1 WITH (electrically NEAR connect$3) WITH (tie NEAR bar$1)) and active	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
28	3	(chip$1 WITH (electrically NEAR connect$3) WITH (tie NEAR bar$1)) and (flip NEAR chip$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
29	3	(chip$1 WITH (electrically NEAR connect$3) WITH (tie NEAR bar$1)) and ((flip NEAR chip$1) and ((lead NEAR frame) WITH (tie NEAR bar$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0:
30	6	("4534105" | "5198886" | "5331203" | "5583370" | "5684330" | "5821615").PN.	USPAT	2004/0:
26	47	chip$1 WITH (electrically NEAR connect$3) WITH (tie NEAR bar$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/0: